

Abbreviations

Public

ASML

ASML Small Talk 2021

Investor Day Virtual



Investor Day – Abbreviations

Abbreviation	Meaning
2D	2 dimensional
3D	3 Dimensional
5G	5th Generation network
Adv	Advanced
AI	Artificial Intelligence
AlTiC	Aluminum-Titanium-Carbon
ArF	Argon Fluoride
ArF-i	Argon Fluoride Immersion
ASP	Average Selling Price
ATP	ASML Test Procedure
BLP	Bit Line Pad
BPR	Buried Power Rail
CAGR	Compound annual growth rate
CapEx	Capital Expenditure
CCD	Charged Couple Device

Abbreviation	Meaning
CD	Critical Dimension
CDU	Critical Dimension Uniformity
CFET	Complementary FET
CMD	Capital Market Day
CO2	Carbon dioxide
CO2e	Carbon dioxide equivalents
CoW	Chip on Wafer
CoWoS	Chip on Wafer on Substrate
CPU	Central Processing Unit
D4C	Design for Control
DBO	Defraction Based Overlay
DCO	Dedicated Chuck Overlay
DOF	Depth of Focus
DRAM	Dynamic Random Access Memory
DTCO	Design Technology Co-Optimization

Investor Day – Abbreviations

Abbreviation	Meaning
DUV	Deep Ultraviolet
e-beam	Electron Beam
EBIT	Earnings Before Interest and Taxes
EEP	Energy Efficiency Performance
ELK	Extreme Low-k
EPE	Edge Placement Error
EPS	Earnings per share
ESG	Environmental Social Governance
ESL	Etch Stop Layer
EUV	Extreme Ultraviolet
Fab	Fabrication plant
FinFET	FIN Field Effect Transistor
FPGA	Field Programmable Grid Array
GaN	Gallium Nitride
GaAs	Gallium Arsenide

Abbreviation	Meaning
GICS	Global Industry Classification Standard
GM	Gross Margin
GPU	Graphics Processing Unit
HBM	High Bandwidth Memory
HKMG	High-k Metal Gate
HMI	Hermes Microvision Inc.
HVM	High Volume Manufacturing
IBM	Installed Base Management
IC	Integrated Circuit
IEDM	International Electron Devices Meeting
IEEE	Institute of Electrical and Electronics Engineers
Imec	Interuniversitair Micro-Elektronica Centrum
incl.	including
InFo	Integrated Fan-Out
IoT	Internet of Things

Investor Day – Abbreviations

Abbreviation	Meaning
IP	Intellectual Property
IRPS	International Reliability Physics Symposium
KrF	Krypton Fluoride laser system
kwspm	x1000 wafer starts per month
LEn	Litho Etch; n number repeats
Litho	Lithography
µm	Micrometer
M&A	Merger and Acquisition
M&I	Metrology & Inspection
max	maximum
min	minimum
mJ	millijoule
mm	millimeter
MMO	Matched Machine Overlay
MP	Metal Pitch

Abbreviation	Meaning
MPT	Multi Paterinning Technology
MPU	Micro Processing Unit
NA	Numerical Aperture
NAND	Not AND - non volatile memory
nm	nanometer
NoN	Node-on-node
NPU	Neural Processing Unit
OPC	Optical Proximity Correction
OPO	On Product Overlay
OVL	Overlay
PC	Personal Computer
PEP	Productivity Enhancement Package
pm	picometer
PP	Poly Pitch
R&D	Research & Development

Investor Day – Abbreviations

Abbreviation	Meaning
RDL	Re Distribution Layer
ROI	Return on investment
S&P	Standard & Poor's Index
SDG	Sustainable Development Goals
SE	Single Exposure
SEM	Scanning Electron Microscope
SEMI	Semiconductor
SG&A	Selling, General and Administrative
SMASH	SMart Alignment Sensor Hybrid (Alignment)
SMO	Source Mask Optimization
SMT	Semiconductor Manufacturing Technology
SNEP	System Node Extension Package
Si	Silicon
SiC	Silicon Carbide
SiGe	Silicon Germanium

Abbreviation	Meaning
SoC	System on Chip
SOI	Silicon On Insulator
SoIC	System on Integrated Chips
SOX	PHLX Semiconductor Sector Index
Spec	Specification
SW	Software
TAM	Total Addressable Market
TPU	Tensor Processing Unit
TPut	Throughput (productivity) upgrade
TSR	Total Shareholder Return
TSV	Through Silicon Vias
UN	United Nations
VHV	Veldhoven
VHV	Vertical-Horizontal-Vertical
WFE	Wafer Fab Equipment

Investor Day – Abbreviations

Abbreviation	Meaning
WoW	Wafer on Wafer
wpd	wafers per day
wph	wafers per hour
WSTS	World Semiconductor Trade Standard
ww	Worldwide
yrs	Years
YS	YieldStar
YTD	Year-to-date
XLD	eXtra Long Down

Forward Looking Statements

This presentation contains statements that are forward-looking, including statements with respect to expected industry and business environment trends including expected growth, outlook and expected financial results, including expected net sales, gross margin, R&D costs, SG&A costs and effective tax rate, annual revenue opportunity for 2025, financial model for 2025 and assumptions and expected growth rates and drivers, expected growth including growth rates 2020-2025 and 2020-2030, total addressable market, growth opportunities beyond 2025 and expected annual growth rate in lithography and metrology and inspection systems and expected annual growth rate in installed base management, expected trends in addressable market up to 2030, expected trends in Logic and Memory revenue opportunities, long term growth opportunities and outlook, expected trends in demand and demand drivers, expected benefits and performance of systems and applications, semiconductor end market trends, expected growth in the semiconductor industry including expected demand growth and capital spend in coming years, expected wafer demand growth and investments in wafer capacity, expected lithography market demand and growth and spend, growth opportunities and drivers, expected trends in EUV and DUV demand, sales, outlook, roadmaps, opportunities and capacity growth and expected EUV adoption, profitability, availability, productivity and output and estimated wafer demand and improvement in value, expected trends in the applications business, expected trends in installed base management including expected revenues and target margins, expected trends and growth opportunity in the applications business, expectations with respect to high-NA, the expectation of increased output capacity, plans, strategies and strategic priorities and direction, expectation to increase capacity, output and production to meet demand, the expectation that Moore's law will continue and Moore's law evolution, product, technology and customer roadmaps, and statements and intentions with respect to capital allocation policy, dividends and share buybacks, including the intention to continue to return significant amounts of cash to shareholders through a combination of share buybacks and growing annualized dividends and statements with respect to ESG commitment, sustainability strategy, targets, initiatives and milestones. You can generally identify these statements by the use of words like "may", "will", "could", "should", "project", "believe", "anticipate", "expect", "plan", "estimate", "forecast", "potential", "intend", "continue", "target", "future", "progress", "goal" and variations of these words or comparable words. These statements are not historical facts, but rather are based on current expectations, estimates, assumptions and projections about our business and our future financial results and readers should not place undue reliance on them. Forward-looking statements do not guarantee future performance and involve a number of substantial known and unknown risks and uncertainties. These risks and uncertainties include, without limitation, economic conditions; product demand and semiconductor equipment industry capacity, worldwide demand and manufacturing capacity utilization for semiconductors, semiconductor end-market trends, the impact of general economic conditions on consumer confidence and demand for our customers' products, performance of our systems, the impact of the COVID-19 outbreak and measures taken to contain it on the global economy and financial markets, as well as on ASML and its customers and suppliers, and other factors that may impact ASML's sales and gross margin, including customer demand and ASML's ability to obtain supplies for its products, the success of R&D programs and technology advances and the pace of new product development and customer acceptance of and demand for new products, production capacity and our ability to increase capacity to meet demand, the number and timing of systems ordered, shipped and recognized in revenue, and the risk of order cancellation or push out, production capacity for our systems including the risk of delays in system production and supply chain capacity, constraints, shortages and disruptions, trends in the semi-conductor industry, our ability to enforce patents and protect intellectual property rights and the outcome of intellectual property disputes and litigation, availability of raw materials, critical manufacturing equipment and qualified employees and trends in labor markets, geopolitical factors, trade environment; import/export and national security regulations and orders and their impact on us, ability to meet sustainability targets, changes in exchange and tax rates, available liquidity and liquidity requirements, our ability to refinance our indebtedness, available cash and distributable reserves for, and other factors impacting, dividend payments and share repurchases, results of the share repurchase programs and other risks indicated in the risk factors included in ASML's Annual Report on Form 20-F for the year ended December 31, 2020 and other filings with and submissions to the US Securities and Exchange Commission. These forward-looking statements are made only as of the date of this document. We undertake no obligation to update any forward-looking statements after the date of this report or to conform such statements to actual results or revised expectations, except as required by law.

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